

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S1	4156	substrate with (porous or porosity or spong\$2) with (resin or encapsula\$5)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 15:54
S2	125	(substrate with (porous or porosity or spong\$2) with (resin or encapsula\$5)) same (chip or die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 15:55
S3	90	S2 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 15:55
S4	34	(substrate or base or layer) with (porous or porosity or sponge or sponge-like or spongy) with (encapsula\$5) with penetrat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:03
S5	96	(porous or porosity or sponge or sponge-like or spongy) with (encapsula\$5) with penetrat\$3	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:04
S6	29	S4 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:04
S8	21	(encapsulant or encapsulat\$3 or resin or epoxy) with (substrate) with (chip or die) with (lock\$3)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:21

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S9	980	((encapsulant or encapsulat\$3 or resin or epoxy) with (substrate) with (lock\$3 or interlock\$3 or seep\$3 or penetrat\$3) with surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:22
S10	157	((encapsulant or encapsulat\$3 or resin or epoxy) with (substrate) with (lock\$3 or interlock\$3 or seep\$3 or penetrat\$3) with surface) same (chip or die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:22
S11	108	S10 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:22
S14	59	(substrate with (sponge or sponge-like)) same (chip or die)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:31
S15	40	S14 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:31
S16	0	(encapsulant or encapsulat\$3 or resin or epoxy) with (penetrat\$3) with (into) with (surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:51
S17	2709	(encapsulant or encapsulat\$3 or resin or epoxy) same (seep or penetrat\$3) same (into or inside) same (surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:51

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S18	379	(encapsulant or encapsulat\$3 or resin or epoxy) with (seep or penetrat\$3) with (into or inside) with (surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:52
S19	320	S18 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:52
S20	383	(encapsulant or encapsulat\$3 or resin or epoxy) with (seep\$3 or penetrat\$3) with (into or inside) with (surface)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:53
S21	8	S20 and (substrate with (porous or porosity or sponge or sponge-like))	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:54
S22	5	S21 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 16:54
S24	3556	438/117.ccls. or 438/118.ccls. or 438/125.ccls. or 438/126.ccls. or 438/127.ccls.	USPAT	OR	ON	2008/01/28 17:19
S25	3179	S24 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2008/01/28 17:19
S26	2260	S25 and (resin or encapsulant or encapsulat\$3)	USPAT	OR	ON	2008/01/28 17:19
S27	1975	S25 and ((resin or encapsulant or encapsulat\$3) same (chip or die or semiconductor))	USPAT	OR	ON	2008/01/28 17:20

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S28	4118	257/787.ccls.	US-PGPUB; USPAT; USOCR; FPRS; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/01/28 17:20
S29	1606	S28 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2008/01/28 17:20
S30	1353	S29 and ((resin or encapsulant or encapsulat\$3) same (chip or die or semiconductor))	USPAT	OR	ON	2008/01/28 17:20
S31	173	257/E23.116 or 257/E23.125 or 257/E23.127 or 257/E23.129 or 257/E21.499 or 257/E21.502	USPAT	OR	ON	2008/01/28 17:26
S32	43	S31 not ("2008".ay. or "2007".ay. or "2006".ay. or "2005".ay. or "2004".ay.)	USPAT	OR	ON	2008/01/28 17:26
S33	8	("20040092129" "20040097081" "20040097086" "20040106235" "20040106288" "5924190" "6358776" "6767767").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/01/28 17:35
S34	3	((("6107679") or ("20010026959") or ("20020028525")).PN.	US-PGPUB; USPAT	OR	OFF	2008/01/28 17:37